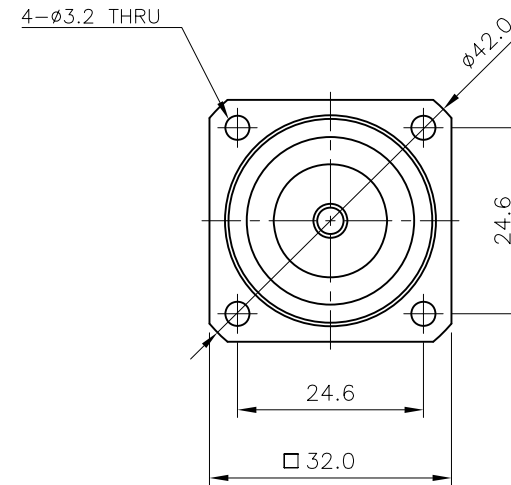
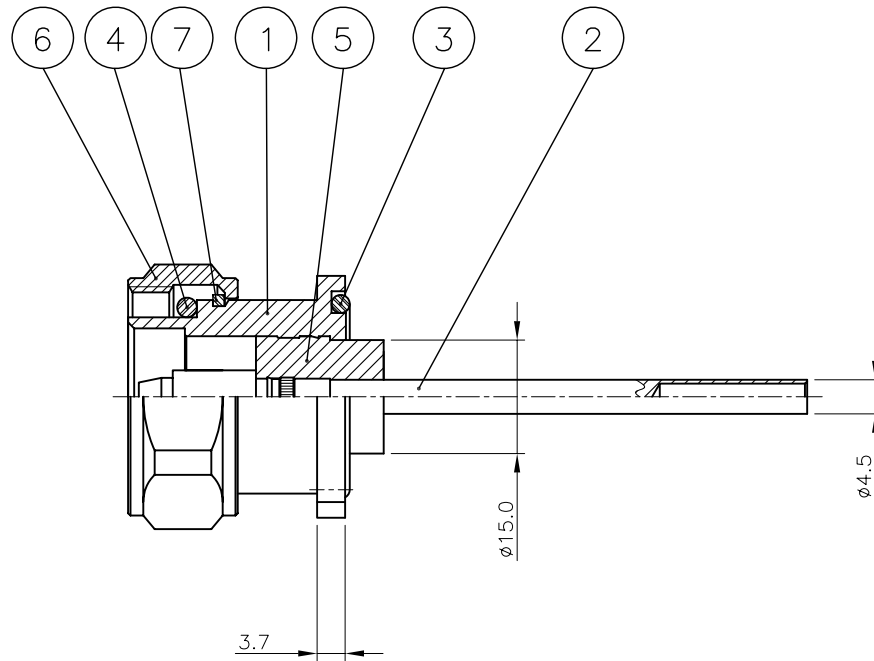


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	T.J.KIM	J.H.YOUN	2014.10.28.
2	도금사양 변경(PIMD 개선)	T.J.KIM	J.H.YOUN	2014.12.12.



7	SPRING RING	1	SUS	부동태처리	DSR01100-5/1
6	CAP	1	MBsBD	SUCO Plate	DCU02190-5/1
5	INSULATOR	1	TEFLON		DIN02462-N/1
4	GASKET	1	SILICONE RUB		DGK00054-N/1
3	GASKET	1	SILICONE RUB		DGK00199-N/1
2	CONTACT	1	MBsBD	Silver Plate (5μm)	DCT03273-5/3
1	BODY	1	MBsBD	SUCO Plate (5μm)	DBD03733-5/4
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2014. 12. 12.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	J.H.YOUN	
MATERIAL		CHECKED BY	S.L.SON	TITLE 7/16 DIN50 SOLDER END JS-4H
		DRAWN BY	T.J.KIM	
FINISH		SCALE	UNIT	DWG NO. CN03330-7/2 REVISION 2 SHEET 1 of 1
		1/1	mm	